

6N137

Features:

- High speed 10Mbit/s
- Guaranteed performance from -40 to 85°C
- · Logic gate output
- High isolation voltage between input and output (Viso=5000 V rms)
- Pb free and RoHS compliant.
- UL approved (No. 214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved (No. 2037145)

Description

The 6N137 consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output.

It is packaged in a 8-pin DIP package and available in wide-lead spacing and SMD options.

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface

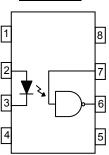
Truth Table (Positive Logic)

Input	Enable	Output
Н	Н	L
L	Н	П
Н	L	Н
L	L	Н
Н	NC	L
L	NC	Н

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Schematic



A 0.1µF bypass capacitor must be connected between pins 8 and 5 *3

Pin Configuration

- 1, No Connection
- 2, Anode
- 3. Cathode
- 4. No Connection
- 5. Gnd
- 6. Vout
- 7, V_E
- 8, V_{CC}



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Absolute Maximum Ratings (T_a=25°C)

	Parameter	Symbol	Rating	Unit
	Forward current	l _F	50	mA
Input	Enable input voltage Not exceed V _{CC} by more than 500mV	V _E	5.5	V
	Reverse voltage	V_{R}	5	V
	Power dissipation	P_{D}	100	mW
	Power dissipation	P _C	85	mW
Out wit	Output current	I _O	50	mA
Output	Output voltage	V_{O}	7.0	V
	Supply voltage	V_{CC}	7.0	V
Output Po	wer Dissipation	Po	100	mW
Isolation v	oltage *1	V_{ISO}	5000	V rms
Operating	temperature	T _{OPR}	-40 ~ +85	°C
Storage te	mperature	T _{STG}	-55 ~ +125	°C
Soldering	temperature *2	T _{SOL}	260	°C

Notes

^{*1} AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1 & 2 are shorted together, and pins 3 & 4 are shorted together.

^{*2} For 10 seconds.



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Electrical Characteristics (T_a=-40 to 85°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward voltage	V_{F}	-	1.4	1.8	V	I _F = 10mA
Reverse voltage	V_R	5.0	-	-	V	I _R = 10μA
Temperature coefficient of forward voltage	$\Delta V_F / \Delta T_A$	-	-1.8	-	mV/°C	I _F =10mA
Input capacitance	C _{IN}	-	60	-	pF	V _F =0, f=1MHz

Output						
Parameter	Symbol	Min.	Тур.*	Max.	Unit	Condition
High level supply current	I _{CCH}	-	7	10	mA	I _F =10mA, V _E =0.5V, V _{CC} =5.5V
Low level supply current	I _{CCL}	ı	9	13	mA	I_F =0mA, V_E =0.5V, V_{CC} =5.5V
High level enable current	I _{EH}	ı	- 0.6	-1.6	mA	V _E =0.5V, V _{CC} =5.5V
Low level enable current	I _{EL}	-	- 0.8	-1.6	mA	V _E =2.0V, V _{CC} =5.5V
High level enable voltage	V_{EH}	2.0	-	-	V	I _F =10mA, V _{CC} =5.5V
Low level enable voltage	V _{EL}	-	-	0.8	٧	I _F =10mA, V _{CC} =5.5V

Transfer Characteristics (T₂=-40 to 85°C unless specified otherwise)

Tansier Characteristics (1a = 40 to 05 0 arriess specified other wise)							
Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition	
HIGH Level Output Current	I _{OH}	-	2.1	100	uA	V _{CC} =5.5V, V _O =5.5V, I _F =250μA, V _E =2.0V	
LOW Level Output Current	V _{OL}	-	0.35	0.6	V	$V_{CC} = 5.5V, I_F = 5mA,$ $V_E = 2.0V, I_{CL} = 13mA$	
Input Threshold Current	I _{FT}	-	2.5	5	mA	V _{CC} = 5.5V, V _O =0.6V, V _E =2.0V,I _{OL} =13mA	



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Switching Characteristics (T_a=-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Witching Characteristics (1a- 40 to 05 C; VCC-5V; IF-7:51117 and cos specified other wise)							
Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition	
Propagation delay time to output High level (Fig.12)	T _{PHL}	-	35	75	ns	$C_L = 15pF, R_L = 350\Omega,$ TA=25°C	
Propagation delay time to output Low level (Fig.12)	T _{PLH}	-	40	75	ns	$C_L = 15pF, R_L = 350\Omega,$ TA=25°C	
Pulse width distortion	Tphl – Tplh	-	5	35	ns	$C_L = 15pF, R_L = 350\Omega$	
Output rise time (Fig.12)	tr	-	40	-	ns	$C_L = 15pF, R_L = 350\Omega$	
Output fall time (Fig.12)	tf	-	10	-	ns	$C_L = 15pF, R_L = 350\Omega$	

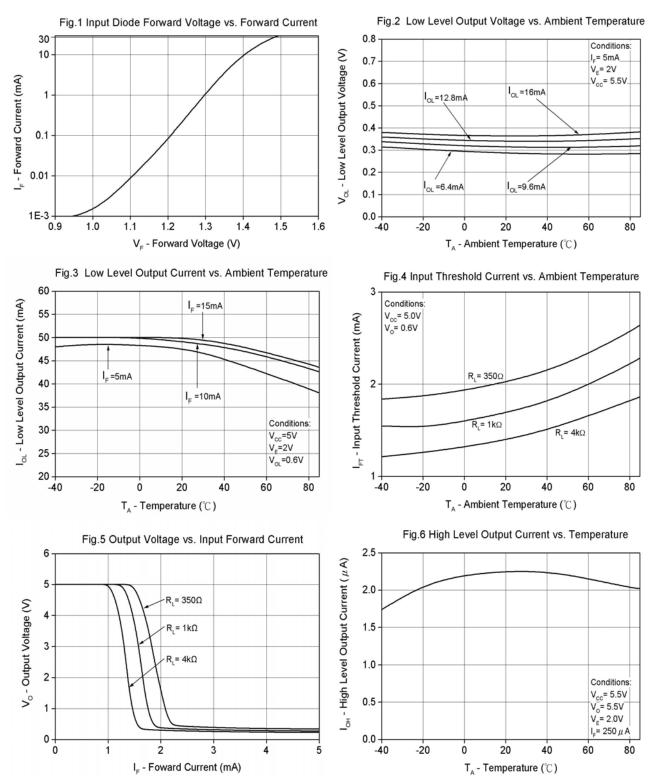
Switching Characteristics (T_a=-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Enable Propagation Delay Time to Output High Level (Fig.13)	t _{ELH}	-	15	-	ns	$I_F = 7.5 \text{mA}$, $V_{EH} = 3.5 \text{V}$, $C_L = 15 \text{pF}$, $R_L = 350 \Omega$
Enable Propagation Delay Time to Output Low Level (Fig.13)	t _{EHL}	ı	15	ı	ns	$I_F = 7.5 \text{mA}$, $V_{EH} = 3.5 \text{V}$, $C_L = 15 \text{pF}$, $R_L = 350 \Omega$
Common Mode Transient Immunity at Logic High *4	СМн	5000	ı	ı	V/µS	I_F = 0mA , V_{CM} =50Vp-p, V_{OH} =2.0V, R_L =350 Ω , TA =25°C
Common Mode Transient Immunity at Logic Low *5	CM _L	5000	ı	ı	V/µS	I_F = 7.5mA , V_{CM} =50Vp-p, V_{OL} =0.8V, R_L =350 Ω , TA =25°C



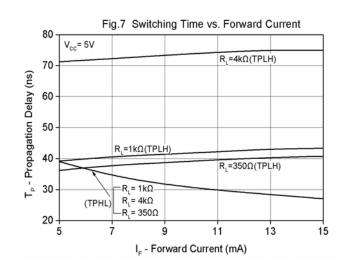
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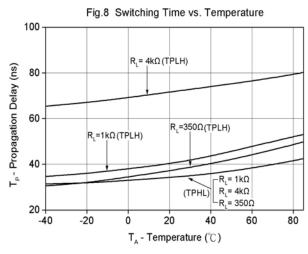
Typical Performance Curves

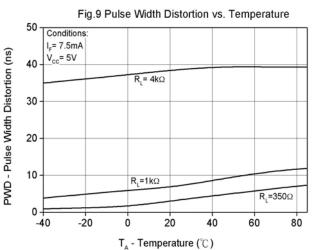


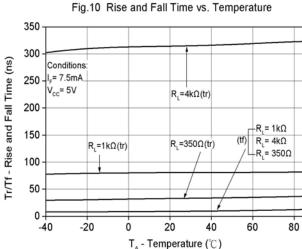


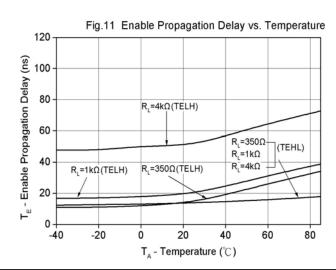
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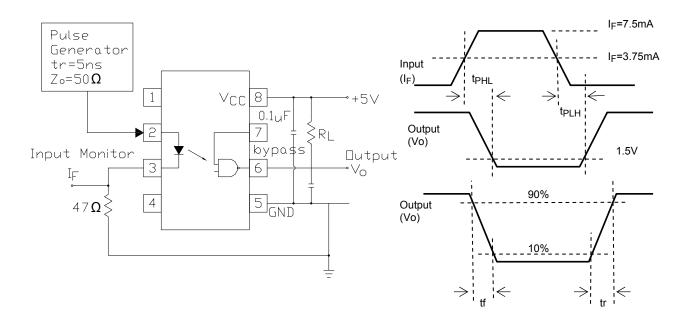


Fig. 12 Test circuit and waveforms for $t_{\text{PHL}},\,t_{\text{PLH}},\,t_{\text{r}},$ and t_{f}

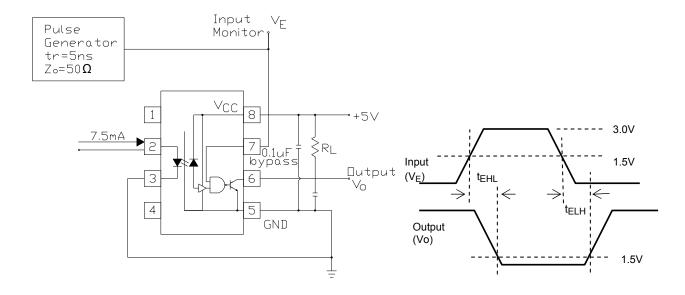


Fig. 13 Test circuit and waveform for tehland telh



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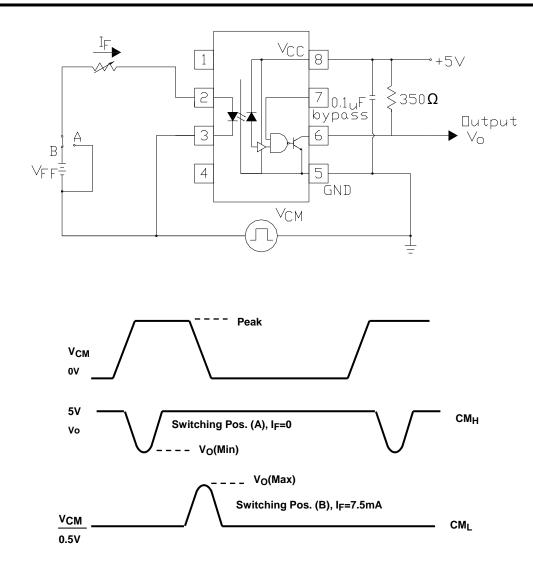


Fig. 14 Test circuit Common mode Transient Immunity

Notes:

- *3 The VCC supply must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package VCC and GND pins
- *4 CMH– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., VOUT > 2.0V).
- *5 CML— The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., VOUT < 0.8V).



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Order Information

Part Number

6N137Y(Z)-V

Note

Y = Lead form option (S, S1, M or none) Z = Tape and reel option (TA, TB or none).

V = VDE (optional)

Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
М	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

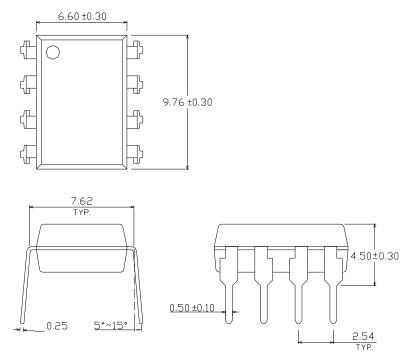


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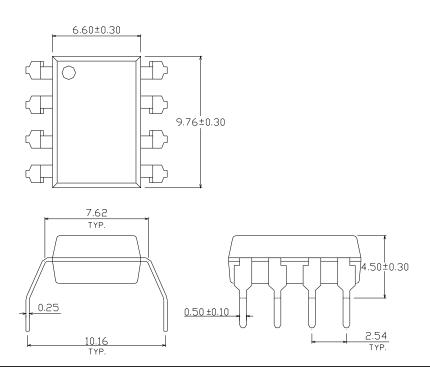
Package Drawing

(Dimensions in mm)

Standard DIP Type



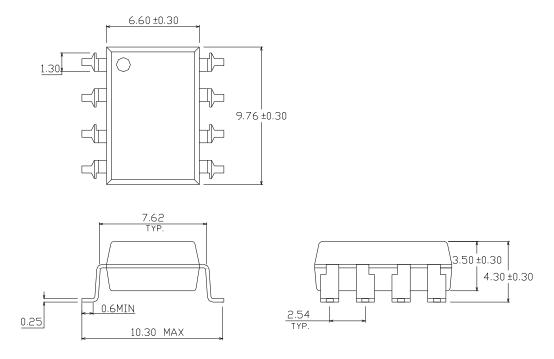
Option M Type



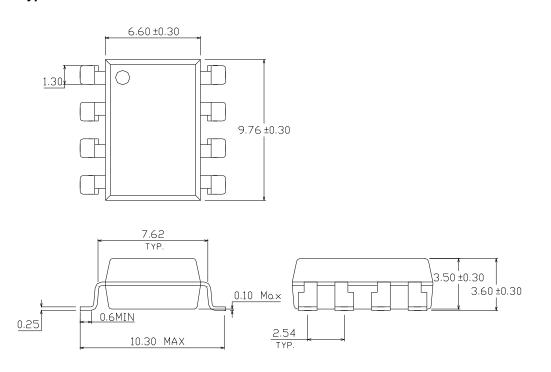


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Option S Type



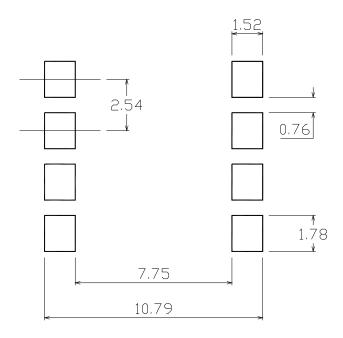
Option S1 Type



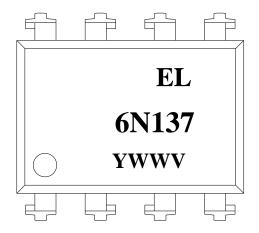


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Recommended pad layout for surface mount leadform



Device Marking



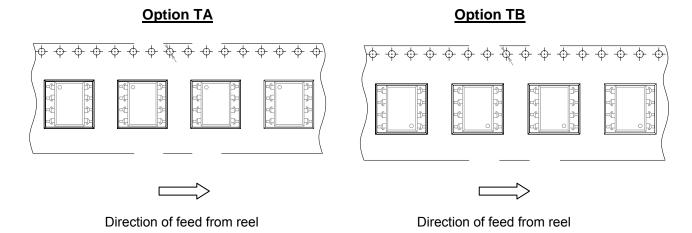
Notes

6N137 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)

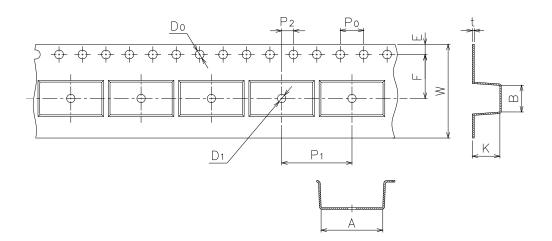


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Tape & Reel Packing Specifications



Tape dimensions

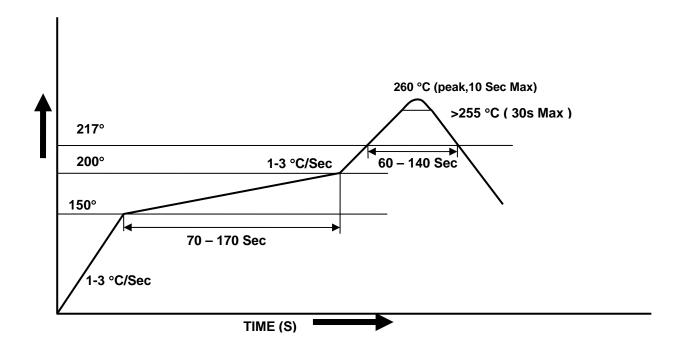


Dimension No.	Α	В	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5±0.1	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	w	K



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Solder Reflow Temperature Profile





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